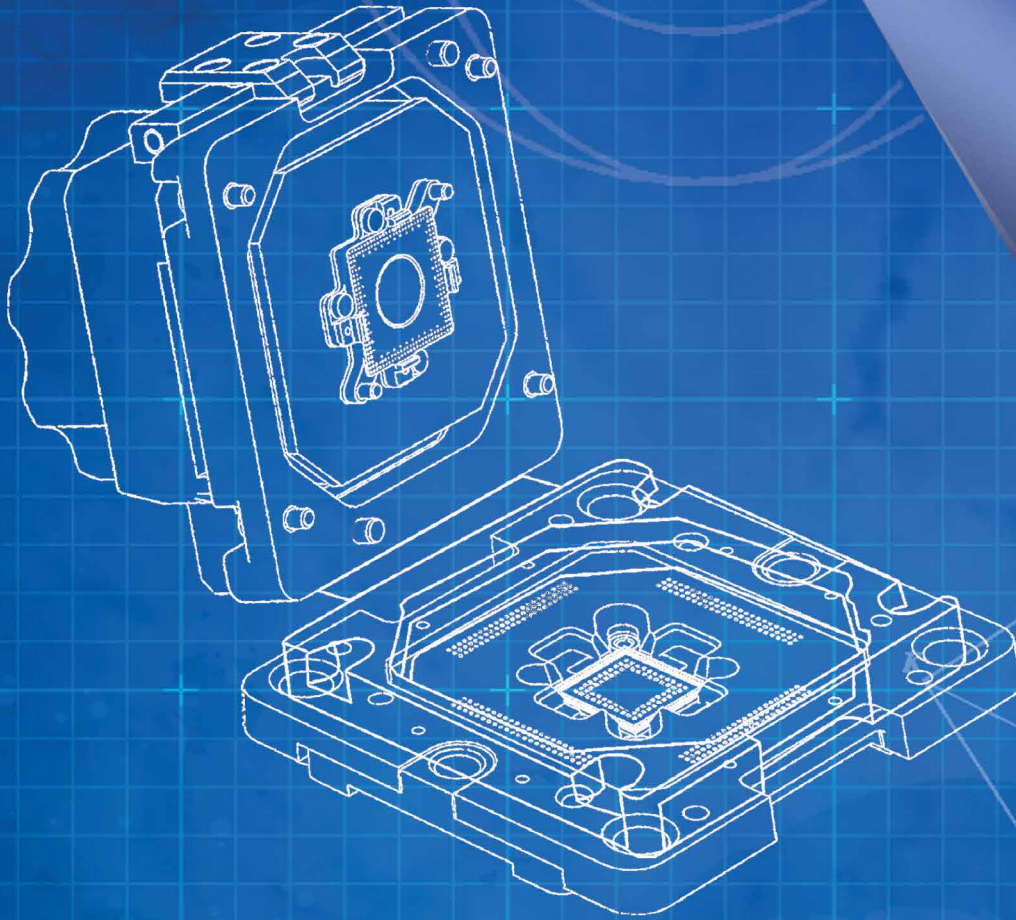


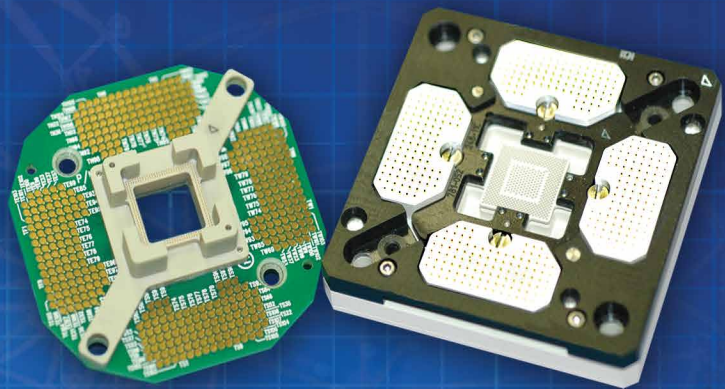
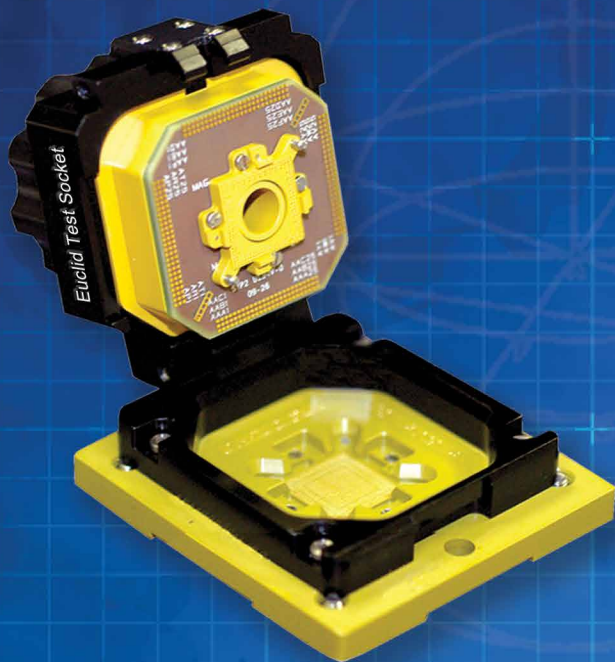
EUCLID

SOCKETS FOR PACKAGE ON PACKAGE TEST

smiths connectors



- ▶ Memory-bearing, memory-less, and manual sockets
- ▶ Advanced alignment features for both top and bottom devices
- ▶ Refined analysis tools that guarantee production-ready solutions
- ▶ Controlled impedance available for maximum signal integrity



EUCLID

TESTING IN THE THIRD DIMENSION

- ▶ The tester or socket must supply the memory function during test through the topside attach features
- ▶ Extreme precision and simultaneous alignment are necessities
- ▶ Solutions must be valid in both manual and automated test environments

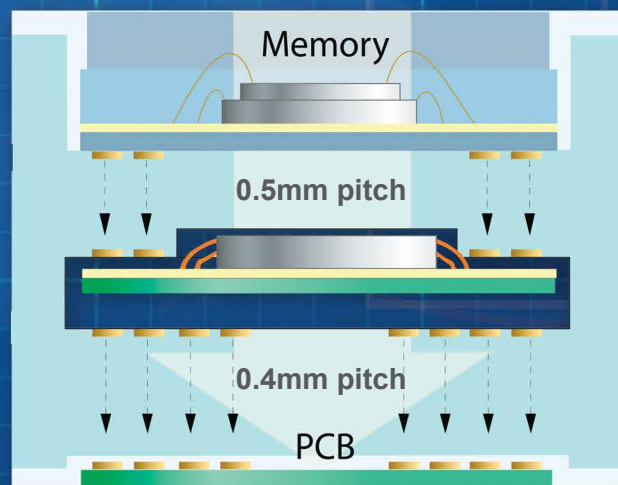
HIGH SPEED MEMORY CHALLENGES

- ▶ Euclid designs feature an optional coaxial interposer for memory-less test
- ▶ RF simulation is used to determine the appropriate signal integrity solution
- ▶ 6 Gbps options available

SOCKETS FOR PACKAGE ON PACKAGE TEST

IDI Euclid Sockets provide reliable solutions for both manual and automated testing of PoP devices. The unique ability of Euclid Sockets to accurately and simultaneously align both the upper and lower device pads increases fault coverage and lowers the cost of test. A mature design process with proven rules and scores of successful implementations solidifies IDI's position as the leader in PoP test solutions.

DUAL SIDED TEST AND SPACE TRANSFORMATION



For more information, visit www.idinet.com/EUCLID